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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

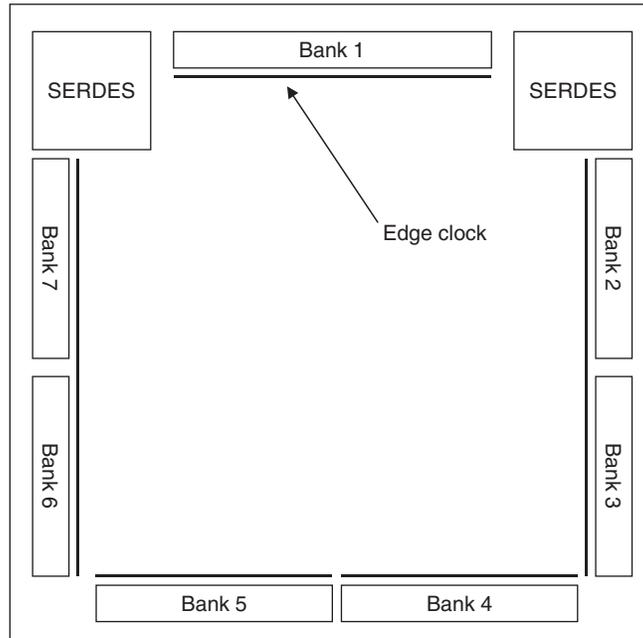
Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	604
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (Tj)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-5ff1152i

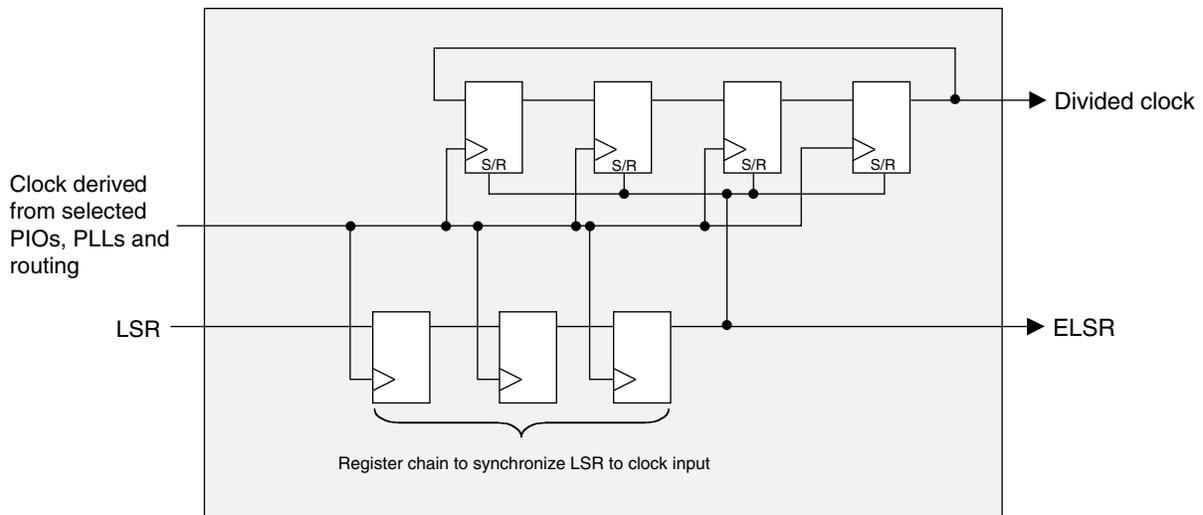
Figure 2-7. Edge Clock Resources



Precision Clock Divider

Each set of edge clocks has four high-speed dividers associated with it. These are intended for generating a slower speed system clock from the high-speed edge clock. The block operates in a DIV2 or DIV4 mode and maintains a known phase relationship between the divided down clock and high-speed clock based on the release of its reset signal. The clock dividers can be fed from selected PIOs, PLLs and routing. The clock divider outputs serve as primary clock sources. This circuit also generates an edge local set/reset (ELSR) signal which is fed to the PIOs via the edge clock network and is used for the rest of the I/O gearing logic.

Figure 2-8. Clock Divider Circuit



Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is

Table 2-6. Input/Output/Tristate Gearing Resource Rules

PIO	Input/Output Logic			Tri-State/Bidi	
	x1	x2	x4	x1	x2/x4
A	?	?	?	?	N/A
B	?	No I/O Logic	No I/O Logic	?	N/A
C	?	?	No I/O Logic	?	N/A
D	?	No I/O Logic	No I/O Logic	?	N/A

Note: Pin can still be used without I/O logic.

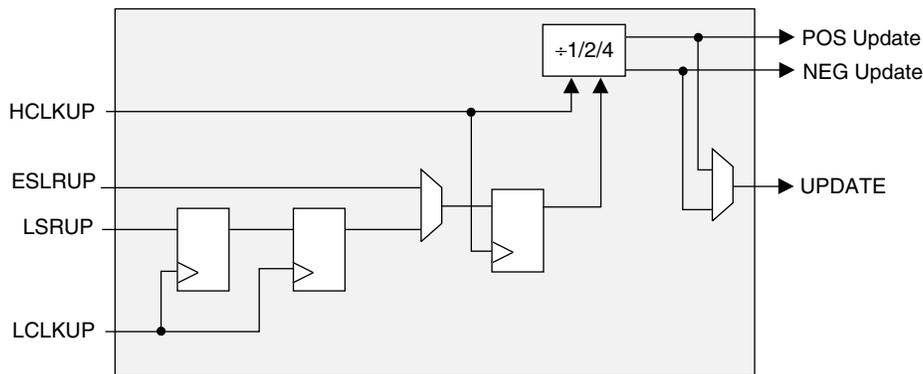
Control Logic Block

The control logic block allows the modification of control signals selected by the routing before they are used in the PIO. It can optionally invert all signals passing through it except the Global Set/Reset. Global Set/Reset can be enabled or disabled. It can route either the edge clock or the clock to the high-speed clock nets. The clock provided to the PIO by routing is used as the slow-speed clocks. In addition this block contains delays that can be inserted in the clock nets to enable Lattice’s unique cycle boosting capability.

Update Block

The update block is used to generate the POS update and NEG update signals used by the DDR/Shift register blocks within the PIO. Note the update block is only required in shift modes. This is required in order to do the high speed to low speed handoff. One of these update signals is also selected and output from the PIC as the signal UPDATE. It consists of a shift chain that operates off either the high-speed input or output clock. The values of each register in the chain are set or reset depending on the desired mode of operation. The set/reset signal is generated from either the edge reset ELSR or the local reset LSR. These signals are optionally inverted by the Control Logic Block and provided to the update block as ELSRUP and LSRUP. The Lattice design tools automatically configure and connect the update block when one of the DDR or shift register primitives is used.

Figure 2-25. Update Block



PURESPEED I/O Buffer

Each I/O is associated with a flexible buffer referred to as PURESPEED I/O buffer. These buffers are arranged around the periphery of the device in seven groups referred to as Banks. The PURESPEED I/O buffers allow users to implement the wide variety of standards that are found in today’s systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL. The availability of programmable on-chip termination for both input and output use, further enhances the utility of these buffers.

3. Bottom Side (Banks 4 and 5)

These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differential Receiver and Driver
Output Standards Supported	LVTTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II SSTL33_I, II HSTL15_I, II, III ¹ , IV ¹ HSTL18_I, II, III ¹ , IV ¹ SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL ² , GTL+ ²	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II HSTL15_I, III HSTL18_I, II, III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL ² , GTL+ ²	LVTTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II SSTL33_I, II HSTL15_I, II, III ¹ , IV ¹ HSTL18_I, II, III ¹ , IV ¹ SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL ² , GTL+ ²	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II HSTL15_I, III HSTL18_I, II, III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL ² , GTL+ ²
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
ALL Support	No	Yes	Yes	Yes

1. Input only.

2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTTL and other standards. The buffers support the LVTTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

Table 2-9. Supported Input Standards

Input Standard	V _{REF} (Nom.)	V _{CCIO} ¹ (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTTL33 ³	—	3.3	None
LVC MOS 33, 25, 18, 15, 12 ³	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33 ³	—	3.3	None
PCIX15	0.75	1.5 ²	None / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8 ²	None / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8 ²	None / V _{CCIO} : 50
HSTL15_I, II	0.75	1.5 ²	None / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5 ²	None / V _{CCIO} : 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5 ²	None / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL18_I, II	0.9	1.8 ²	None / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2 ²	None / V _{CCIO} : 50
Differential Interfaces			
SSTL18D_I, II	—	1.8 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL25D_I, II	—	2.5 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL18D_I, II	—	1.8 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} /2: 50, 60/ V _{TT} : 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V _{CMT} : 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RSDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.

2. V_{CCIO} needed for on-chip termination to V_{CCIO}/2 or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.

3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

Figure 2-27. Output Termination Schemes

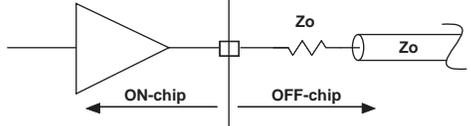
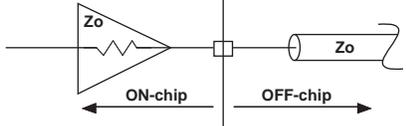
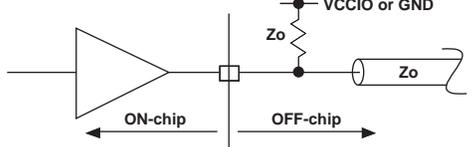
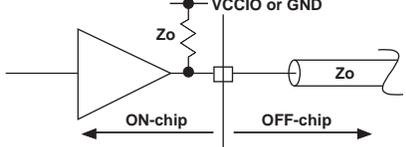
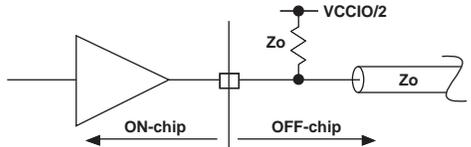
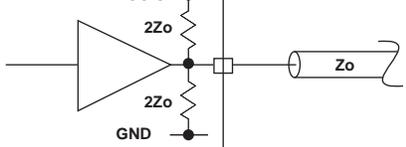
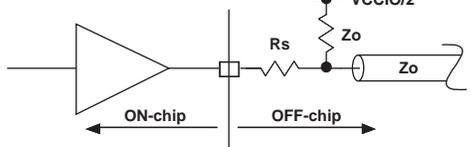
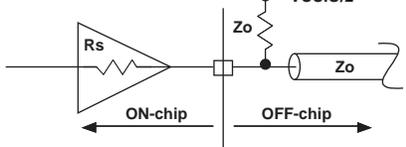
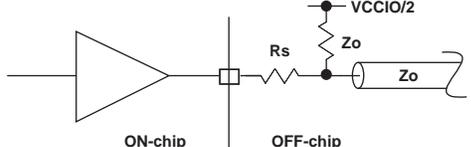
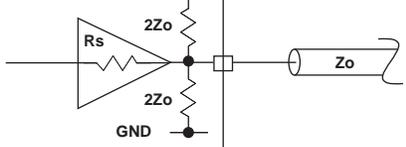
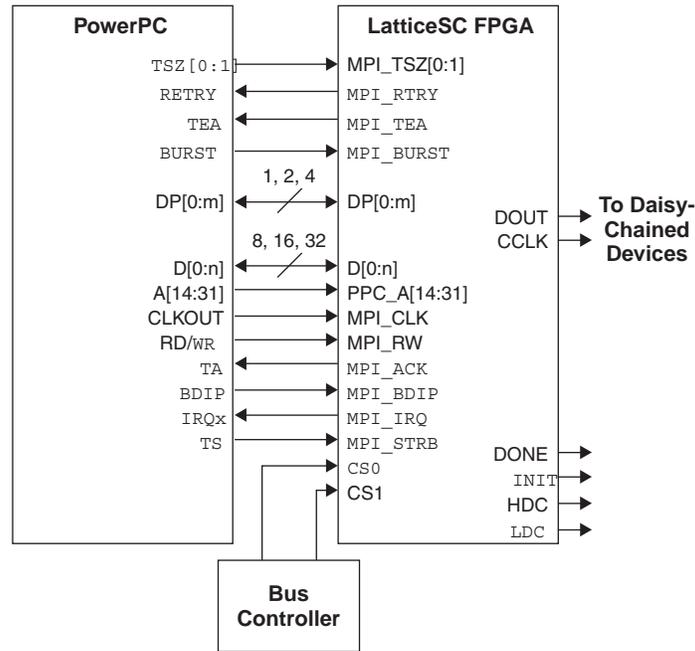
Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V _{CCIO} or parallel driving end		
Parallel termination to V _{CCIO} /2 driving end		
Combined series + parallel termination to V _{CCIO} /2 at driving end (only series termination moved on-chip)		
Combined series + parallel to V _{CCIO} /2 driving end		

Figure 2-32. PowerPCI and MPI Schematic



Configuration and Testing

The following section describes the configuration and testing features of the LatticeSC family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeSC devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS33, 25 and 18 standards. For additional detail refer to technical information at the end of the data sheet.

Device Configuration

All LatticeSC devices contain three possible ports that can be used for device configuration. The serial port, which supports bit-wide configuration, and the sysCONFIG port that supports both byte-wide and serial configuration. The MPI port supports 8-bit, 16-bit or 32-bit configuration.

The serial port supports both the IEEE Std. 1149.1 Boundary Scan specification and the IEEE Std. 1532 In-System Configuration specification. The sysCONFIG port is a 20-pin interface with six of the I/Os used as dedicated pins and the rest being dual-use pins. When sysCONFIG mode is not used, these dual-use pins are available for general purpose I/O. All I/Os for the sysCONFIG and MPI ports are in I/O bank #1.

On power-up, the FPGA SRAM is ready to be configured with the sysCONFIG port active. The IEEE 1149.1 serial mode can be activated any time after power-up by sending the appropriate command through the TAP port. Once a configuration port is selected, that port is locked and another configuration port cannot be activated until the next re-initialization sequence. For additional detail refer to technical information at the end of the data sheet.

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/ μ s
			—	—	75	ms

- See the Power-up and Power-Down requirements section for more details on power sequencing.
- From 0.5V to minimum operating voltage.

Hot Socketing Specifications¹

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current ^{2, 3, 4, 5, 6}	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	± 1500	μ A
I_{HDIN}	SERDES average input current when device powered down and inputs driven ⁷		—	—	4	mA

- See Hot Socket power up/down information in Chapter 2 of this document.
- Assumes monotonic rise/fall rates for all power supplies.
- Sensitive to power supply sequencing as described in hot socketing section.
- Assumes power supplies are between 0 and maximum recommended operations conditions.
- IDK is additive to I_{PU} , I_{PD} or I_{BH} .
- Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
- Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics⁵

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min. ³	Typ.	Max.	Units
$I_{\text{IL}}, I_{\text{IH}}^1$	Input or I/O Low leakage	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	10	μ A
I_{PU}	I/O Active Pull-up Current	$0 \leq V_{\text{IN}} \leq 0.7 V_{\text{CCIO}}$	-30	—	-210	μ A
I_{PD}	I/O Active Pull-down Current	$V_{\text{IL}} (\text{MAX}) \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	30	—	210	μ A
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{\text{IN}} = V_{\text{IL}} (\text{MAX})$	30	—	—	μ A
I_{BHHS}	Bus Hold High Sustaining Current	$V_{\text{IN}} = 0.7V_{\text{CCIO}}$	-30	—	—	μ A
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	210	μ A
I_{BHLH}	Bus Hold High Overdrive Current	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	—	—	-210	μ A
I_{CL}	PCI Low Clamp Current	$-3 < V_{\text{IN}} \leq -1$	$-25 + (V_{\text{IN}} + 1)/0.015$	—	—	mA
I_{CH}	PCI High Clamp Current	$V_{\text{CC}} + 4 > V_{\text{IN}} \geq V_{\text{CC}} + 1$	$25 + (V_{\text{IN}} - V_{\text{CC}} - 1)/0.015$	—	—	mA
V_{BHT}	Bus Hold trip Points	$0 \leq V_{\text{IN}} \leq V_{\text{IH}} (\text{MAX})$	$V_{\text{IL}} (\text{MAX})$	—	$V_{\text{IH}} (\text{MIN})$	V
C1	I/O Capacitance ²	$V_{\text{CCIO}} = 3.3\text{V}, 2.5\text{V}, 1.8\text{V}, 1.5\text{V}, 1.2\text{V},$ $V_{\text{CC}} = 1.2\text{V}, V_{\text{CCIP2}} = 1.2\text{V},$ $V_{\text{CCAUX}} = 2.5, V_{\text{IO}} = 0 \text{ to } V_{\text{IH}} (\text{MAX})$	—	8	—	pf
C3 ²	Dedicated Input Capacitance ²	$V_{\text{CCIO}} = 3.3\text{V}, 2.5\text{V}, 1.8\text{V}, 1.5\text{V}, 1.2\text{V},$ $V_{\text{CC}} = 1.2\text{V}, V_{\text{CCIP2}} = 1.2\text{V},$ $V_{\text{CCAUX}} = 2.5, V_{\text{IO}} = 0 \text{ to } V_{\text{IH}} (\text{MAX})$	—	6	—	pf

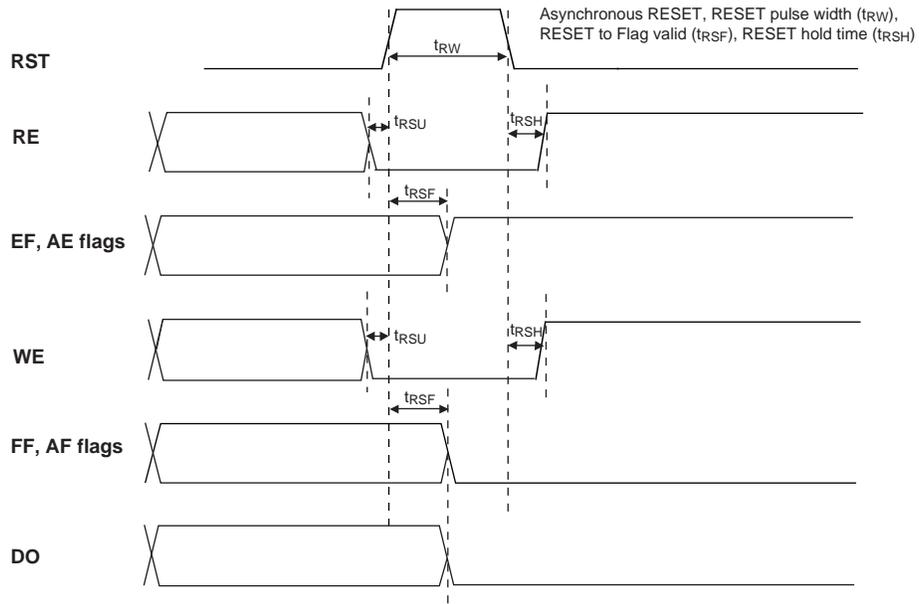
- Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
- $T_{\text{A}} = 25^{\circ}\text{C}$, $f = 1.0\text{MHz}$
- $I_{\text{PU}}, I_{\text{PD}}, I_{\text{BHLS}}$ and I_{BHHS} have minimum values of 15 or $-15\mu\text{A}$ if V_{CCIO} is set to 1.2V nominal.
- This table does not apply to SERDES pins.
- For programmable I/Os.

LatticeSC/M Internal Timing Parameters¹

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

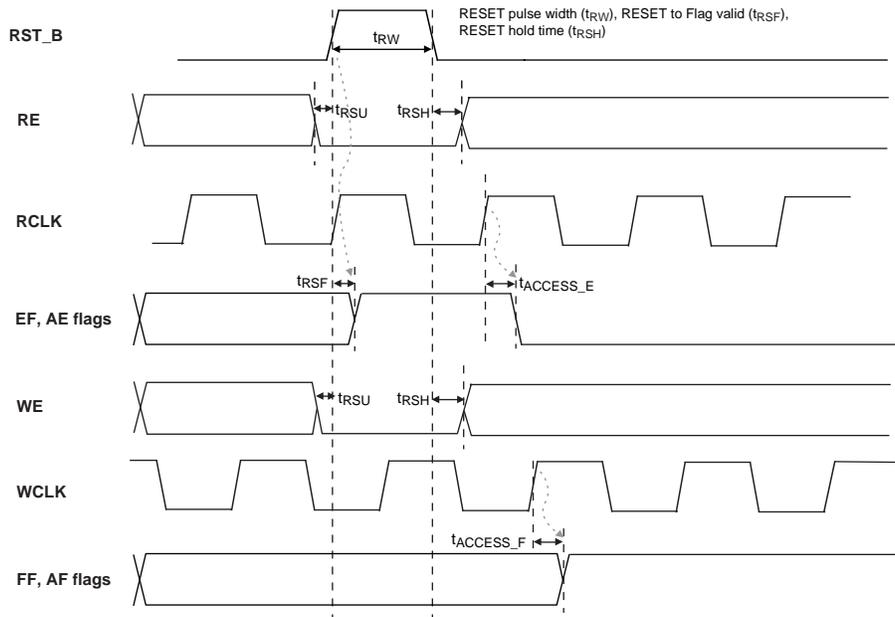
Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
PFU Logic Mode Timing									
t _{LUT4_PFU}	CTOF_DEL	LUT4 delay (A to D inputs to F output)	—	0.045	—	0.050	—	0.054	ns
t _{LUT5_PFU}	MTOOFX_DEL	LUT5 delay (inputs to output)	—	0.152	—	0.172	—	0.192	ns
t _{LSR_PFU}	LSR_DEL	Set/Reset to output (asynchronous)	—	0.378	—	0.426	—	0.474	ns
t _{SUM_PFU}	M_SET	Clock to Mux (M0,M1) input setup time	0.113	—	0.131	—	0.148	—	ns
t _{HM_PFU}	M_HLD	Clock to Mux (M0,M1) input hold time	-0.041	—	-0.046	—	-0.052	—	ns
t _{SUD_PFU}	DIN_SET	Clock to D input setup time	0.072	—	0.083	—	0.094	—	ns
t _{HD_PFU}	DIN_HLD	Clock to D input hold time	-0.028	—	-0.032	—	-0.035	—	ns
t _{CK2Q_PFU}	REG_DEL	Clock to Q delay, D-type register configuration	—	0.224	—	0.252	—	0.279	ns
t _{LE2Q_PFU}	LTCH_DEL	Clock to Q delay latch configuration	—	0.294	—	0.331	—	0.367	ns
t _{LD2Q_PFU}	TLTCH_DEL	D to Q throughput delay when latch is enabled	—	0.300	—	0.338	—	0.376	ns
PFU Memory Mode Timing									
t _{CORAM_PFU}	CLKTOF_DEL	Clock to Output	—	0.575	—	0.649	—	0.724	ns
t _{SUDATA_PFU}	DIN_SET	Data Setup Time	-0.024	—	-0.026	—	-0.027	—	ns
t _{HDATA_PFU}	DIN_HLD	Data Hold Time	0.075	—	0.084	—	0.094	—	ns
t _{SUADDR_PFU}	WAD_SET	Address Setup Time	-0.176	—	-0.196	—	-0.215	—	ns
t _{HADDR_PFU}	WAD_HLD	Address Hold Time	0.110	—	0.124	—	0.138	—	ns
t _{SUWREN_PFU}	WE_SET	Write/Read Enable Setup Time	0.014	—	0.019	—	0.024	—	ns
t _{HWREN_PFU}	WE_HLD	Write/Read Enable Hold Time	0.078	—	0.086	—	0.094	—	ns
PIC Timing									
PIO Input/Output Buffer Timing									
t _{IN_PIO}	IN_DEL	Input Buffer Delay(LVCMOS25)	—	0.578	—	0.661	—	0.744	ns
t _{OUT_PIO}	DOPADI_DEL	Output Buffer Delay(LVCMOS25)	—	2.712	—	3.027	—	3.395	ns
t _{SUI_PIO}	DIN_SET	Input Register Setup Time (Data Before Clock)	0.277	—	0.312	—	0.348	—	ns
t _{HI_PIO}	DIN_HLD	Input Register Hold Time (Data after Clock)	-0.267	—	-0.306	—	-0.345	—	ns
t _{COO_PIO}	CK_DEL	Output Register Clock to Output Delay	—	0.513	—	0.571	—	0.639	ns
t _{SUCE_PIO}	CE_SET	Input Register Clock Enable Setup Time	—	0.000	—	0.000	—	0.000	ns
t _{HCE_PIO}	CE_HLD	Input Register Clock Enable Hold Time	—	0.129	—	0.145	—	0.161	ns
t _{SULSR_PIO}	LSR_SET	Set/Reset Setup Time	0.057	—	0.060	—	0.063	—	ns
t _{HLSR_PIO}	LSR_HLD	Set/Reset Hold Time	-0.151	—	-0.159	—	-0.169	—	ns
t _{LE2Q_PIO}	CK_DEL	Input Register Clock to Q delay latch configuration	—	0.335	—	0.372	—	0.410	ns
t _{LD2Q_PIO}	DIN_DEL	Input Register D to Q throughput delay when latch is enabled	—	0.578	—	0.647	—	0.717	ns

Figure 3-10. FIFO Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Figure 3-11. Read Pointer Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Switching Test Conditions

Figure 3-15 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Table 3-4.

Figure 3-15. Output Test Load, LVTTTL and LVCMOS Standards

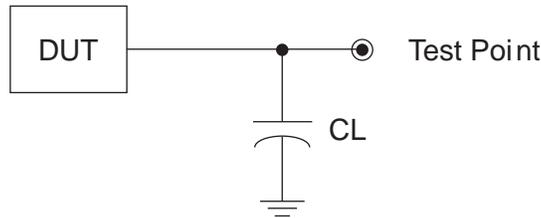


Table 3-4. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	C _L	Timing Ref.	V _T
LVTTTL and other LVCMOS settings (L -> H, H -> L)	30pF	LVCMOS 3.3 = 1.5V	—
		LVCMOS 2.5 = V _{CCIO} /2	—
		LVCMOS 1.8 = V _{CCIO} /2	—
		LVCMOS 1.5 = V _{CCIO} /2	—
		LVCMOS 1.2 = V _{CCIO} /2	—
LVCMOS 2.5 I/O (Z -> H)	30pF	V _{CCIO} /2	V _{OL}
LVCMOS 2.5 I/O (Z -> L)		V _{CCIO} /2	V _{OH}
LVCMOS 2.5 I/O (H -> Z)		V _{OH} - 0.15	V _{OL}
LVCMOS 2.5 I/O (L -> Z)		V _{OL} + 0.15	V _{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AF4	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D	PB3C	5	LLC_DLLT_IN_C/LLC_DLLT_FB_D
AE5	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D	PB3D	5	LLC_DLLC_IN_C/LLC_DLLC_FB_D
AG3	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C	PB4A	5	LLC_DLLT_IN_D/LLC_DLLT_FB_C
AH2	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C	PB4B	5	LLC_DLLC_IN_D/LLC_DLLC_FB_C
AD6	PB4C	5		PB4C	5	
AJ2	PB5A	5		PB5A	5	
AK2	PB5B	5		PB5B	5	
AD7	PB5C	5		PB5C	5	
AD8	PB5D	5	VREF1_5	PB5D	5	VREF1_5
AH3	PB7A	5		PB11A	5	
AJ3	PB7B	5		PB11B	5	
AF9	PB7C	5		PB11C	5	
AE10	PB7D	5		PB11D	5	
AK3	PB8A	5		PB12A	5	
AJ4	PB8B	5		PB12B	5	
AE11	PB9A	5		PB13A	5	
AF10	PB9B	5		PB13B	5	
AK4	PB11A	5		PB16A	5	
AK5	PB11B	5		PB16B	5	
AH10	PB12A	5	PCLKT5_3	PB20A	5	PCLKT5_3
AH11	PB12B	5	PCLKC5_3	PB20B	5	PCLKC5_3
AF13	PB12C	5	PCLKT5_4	PB20C	5	PCLKT5_4
AE14	PB12D	5	PCLKC5_4	PB20D	5	PCLKC5_4
AK6	PB13A	5	PCLKT5_5	PB21A	5	PCLKT5_5
AK7	PB13B	5	PCLKC5_5	PB21B	5	PCLKC5_5
AF14	PB13C	5		PB21C	5	
AJ11	PB15A	5	PCLKT5_0	PB23A	5	PCLKT5_0
AJ12	PB15B	5	PCLKC5_0	PB23B	5	PCLKC5_0
AH13	PB15D	5	VREF2_5	PB23D	5	VREF2_5
AK8	PB16A	5	PCLKT5_1	PB24A	5	PCLKT5_1
AK9	PB16B	5	PCLKC5_1	PB24B	5	PCLKC5_1
AH14	PB17A	5	PCLKT5_2	PB25A	5	PCLKT5_2
AG14	PB17B	5	PCLKC5_2	PB25B	5	PCLKC5_2
AK10	PB19A	5		PB28A	5	
AK11	PB19B	5		PB28B	5	
AH15	PB20A	5		PB29A	5	
AG15	PB20B	5		PB29B	5	
AH12	PB21A	5		PB31A	5	
AJ13	PB21B	5		PB31B	5	
AD15	PB21C	5		PB31C	5	
AE15	PB21D	5		PB31D	5	
AK12	PB23A	5		PB32A	5	
AK13	PB23B	5		PB32B	5	
AJ14	PB24A	5		PB33A	5	
AJ15	PB24B	5		PB33B	5	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AL11	GND	-		GND	-	
AL17	GND	-		GND	-	
AL21	GND	-		GND	-	
AL27	GND	-		GND	-	
AL5	GND	-		GND	-	
AM14	GND	-		GND	-	
AM18	GND	-		GND	-	
AM24	GND	-		GND	-	
AM30	GND	-		GND	-	
AM8	GND	-		GND	-	
AN1	GND	-		GND	-	
AN34	GND	-		GND	-	
AP2	GND	-		GND	-	
AP33	GND	-		GND	-	
B1	GND	-		GND	-	
B34	GND	-		GND	-	
C11	GND	-		GND	-	
C12	GND	-		GND	-	
C13	GND	-		GND	-	
C14	GND	-		GND	-	
C17	GND	-		GND	-	
C21	GND	-		GND	-	
C22	GND	-		GND	-	
C23	GND	-		GND	-	
C24	GND	-		GND	-	
C26	GND	-		GND	-	
C27	GND	-		GND	-	
C30	GND	-		GND	-	
C31	GND	-		GND	-	
C4	GND	-		GND	-	
C5	GND	-		GND	-	
C8	GND	-		GND	-	
C9	GND	-		GND	-	
D18	GND	-		GND	-	
E32	GND	-		GND	-	
E4	GND	-		GND	-	
F19	GND	-		GND	-	
G16	GND	-		GND	-	
G29	GND	-		GND	-	
G7	GND	-		GND	-	
H3	GND	-		GND	-	
H31	GND	-		GND	-	
J10	GND	-		GND	-	
J15	GND	-		GND	-	
J26	GND	-		GND	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
N27	PL47C	7	
P27	PL47D	7	
K33	PL49A	7	
L33	PL49B	7	
M30	PL49C	7	
N30	PL49D	7	
M31	PL51A	7	
N31	PL51B	7	
P24	PL51C	7	
R24	PL51D	7	
M33	PL56A	7	
N33	PL56B	7	
U25	PL56C	7	
T25	PL56D	7	
L34	PL57A	7	
M34	PL57B	7	
P29	PL57C	7	
R29	PL57D	7	
N34	PL60A	7	
P34	PL60B	7	
R27	PL60C	7	
T27	PL60D	7	
R32	PL61A	7	PCLKT7_1
R31	PL61B	7	PCLKC7_1
U24	PL61C	7	PCLKT7_3
T24	PL61D	7	PCLKC7_3
P33	PL62A	7	PCLKT7_0
R33	PL62B	7	PCLKC7_0
T26	PL62C	7	PCLKT7_2
U26	PL62D	7	PCLKC7_2
T32	PL64A	6	PCLKT6_0
T31	PL64B	6	PCLKC6_0
U29	PL64C	6	PCLKT6_1
V29	PL64D	6	PCLKC6_1
T30	PL65A	6	
U30	PL65B	6	
U27	PL65C	6	PCLKT6_3
V27	PL65D	6	PCLKC6_3
R34	PL66A	6	
T34	PL66B	6	
U28	PL66C	6	PCLKT6_2
V28	PL66D	6	PCLKC6_2
V30	PL69A	6	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1,2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
F6	A_VDDOB0_R	-	
B4	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
F7	A_VDDOB1_R	-	
B5	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
E6	VCC12	-	
A5	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
B6	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
A6	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
C6	VCC12	-	
D4	A_VDDIB1_R	-	
C7	VCC12	-	
D5	A_VDDIB2_R	-	
A7	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
B7	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
E7	VCC12	-	
A8	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
F8	A_VDDOB2_R	-	
B8	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
F9	A_VDDOB3_R	-	
B9	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
E8	VCC12	-	
A9	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
B10	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
A10	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
C10	VCC12	-	
D6	A_VDDIB3_R	-	
G10	VCC12	-	
D7	B_VDDIB0_R	-	
E10	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
F10	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
K10	VCC12	-	
A11	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D10	B_VDDOB0_R	-	
B11	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D11	B_VDDOB1_R	-	
B12	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L10	VCC12	-	
A12	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
F11	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
E11	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
G11	VCC12	-	
D8	B_VDDIB1_R	-	
G12	VCC12	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
J17	PT81C	1	D20/PCLKT1_2/MPI_DATA20
D16	PT81B	1	MCA_CLK_P1_OUT
E16	PT81A	1	MCA_CLK_P1_IN
H15	PT78D	1	D21/PCLKC1_1/MPI_DATA21
H16	PT78C	1	D22/PCLKT1_1/MPI_DATA22
C15	PT78B	1	MCA_CLK_P2_OUT
C16	PT78A	1	MCA_CLK_P2_IN
L17	PT75D	1	MCA_DONE_OUT
K17	PT75C	1	BUSYN/RCLK/SCK
E17	PT75B	1	DP0/MPI_PAR0
F17	PT75A	1	MPI_TA
G17	PT73D	1	D23/MPI_DATA23
H17	PT73C	1	DP2/MPI_PAR2
A17	PT73B	1	PCLKC1_0
B17	PT73A	1	PCLKT1_0/MPI_CLK
G18	PT71D	1	DP3/PCLKC1_4/MPI_PAR3
H18	PT71C	1	D24/PCLKT1_4/MPI_DATA24
E18	PT71B	1	MPI_RETRY
F18	PT71A	1	A0/MPI_ADDR14
J18	PT69D	1	A1/MPI_ADDR15
J19	PT69C	1	A2/MPI_ADDR16
C20	PT69B	1	A3/MPI_ADDR17
C19	PT69A	1	A4/MPI_ADDR18
K18	PT66D	1	D25/PCLKC1_5/MPI_DATA25
L18	PT66C	1	D26/PCLKT1_5/MPI_DATA26
D19	PT66B	1	A5/MPI_ADDR19
E19	PT66A	1	A6/MPI_ADDR20
H19	PT63D	1	D27/MPI_DATA27
H20	PT63C	1	VREF1_1
A18	PT63B	1	A7/MPI_ADDR21
B18	PT63A	1	A8/MPI_ADDR22
H21	PT61D	1	D28/PCLKC1_6/MPI_DATA28
J21	PT61C	1	D29/PCLKT1_6/MPI_DATA29
A19	PT61B	1	A9/MPI_ADDR23
B19	PT61A	1	A10/MPI_ADDR24
H22	PT58D	1	D30/PCLKC1_7/MPI_DATA30
J22	PT58C	1	D31/PCLKT1_7/MPI_DATA31
F20	PT58B	1	A11/MPI_ADDR25
G20	PT58A	1	A12/MPI_ADDR26
K21	PT57D	1	D11/MPI_DATA11
K22	PT57C	1	D12/MPI_DATA12
A20	PT57B	1	A13/MPI_ADDR27
B20	PT57A	1	A14/MPI_ADDR28

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
BA19	PB73A	4		PB87A	4	
BA18	PB73B	4		PB87B	4	
AU19	PB73C	4		PB87C	4	
AU18	PB73D	4		PB87D	4	
AV19	PB74A	4	PCLKT4_2	PB89A	4	PCLKT4_2
AV18	PB74B	4	PCLKC4_2	PB89B	4	PCLKC4_2
AN19	PB74C	4	PCLKT4_7	PB89C	4	PCLKT4_7
AP19	PB74D	4	PCLKC4_7	PB89D	4	PCLKC4_7
BB17	PB75A	4	PCLKT4_1	PB90A	4	PCLKT4_1
BB16	PB75B	4	PCLKC4_1	PB90B	4	PCLKC4_1
AT19	PB75C	4	PCLKT4_6	PB90C	4	PCLKT4_6
AT18	PB75D	4	PCLKC4_6	PB90D	4	PCLKC4_6
BA17	PB77A	4	PCLKT4_0	PB91A	4	PCLKT4_0
BA16	PB77B	4	PCLKC4_0	PB91B	4	PCLKC4_0
AR19	PB77C	4	VREF2_4	PB91C	4	VREF2_4
AR18	PB77D	4		PB91D	4	
AY17	PB79A	4	PCLKT4_5	PB93A	4	PCLKT4_5
AY16	PB79B	4	PCLKC4_5	PB93B	4	PCLKC4_5
AN18	PB79C	4		PB93C	4	
AP18	PB79D	4		PB93D	4	
AW17	PB80A	4	PCLKT4_3	PB94A	4	PCLKT4_3
AW16	PB80B	4	PCLKC4_3	PB94B	4	PCLKC4_3
AU17	PB80C	4	PCLKT4_4	PB94C	4	PCLKT4_4
AU16	PB80D	4	PCLKC4_4	PB94D	4	PCLKC4_4
AV17	PB81A	4		PB95A	4	
AV16	PB81B	4		PB95B	4	
AL18	PB81C	4		PB95C	4	
AM18	PB81D	4		PB95D	4	
BB15	PB83A	4		PB97A	4	
BB14	PB83B	4		PB97B	4	
AP17	PB83C	4		PB97C	4	
AN17	PB83D	4		PB97D	4	
BA15	PB84A	4		PB98A	4	
BA14	PB84B	4		PB98B	4	
AT16	PB84C	4		PB98C	4	
AT15	PB84D	4		PB98D	4	
AV15	PB85A	4		PB99A	4	
AV14	PB85B	4		PB99B	4	
AR16	PB85C	4		PB99C	4	
AR15	PB85D	4		PB99D	4	
AY14	PB87A	4		PB101A	4	
AY13	PB87B	4		PB101B	4	
AU15	PB87C	4		PB101C	4	
AU14	PB87D	4		PB101D	4	
BB13	PB88A	4		PB102A	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AE1	PR74A	3		PR88A	3	
AF12	PR73D	3		PR87D	3	
AE12	PR73C	3		PR87C	3	
AF2	PR73B	3		PR87B	3	
AE2	PR73A	3		PR87A	3	
AF11	PR72D	3		PR86D	3	
AE11	PR72C	3		PR86C	3	
AF5	PR72B	3		PR86B	3	
AE5	PR72A	3		PR86A	3	
AF10	PR69D	3		PR83D	3	
AE10	PR69C	3		PR83C	3	
AD1	PR69B	3		PR83B	3	
AC1	PR69A	3		PR83A	3	
AF9	PR68D	3		PR82D	3	
AE9	PR68C	3		PR82C	3	
AD2	PR68B	3		PR82B	3	
AC2	PR68A	3		PR82A	3	
AF6	PR67D	3		PR81D	3	
AE6	PR67C	3		PR81C	3	
AD3	PR67B	3		PR81B	3	
AC3	PR67A	3		PR81A	3	
AE8	PR65D	3		PR79D	3	
AD8	PR65C	3		PR79C	3	
AD4	PR65B	3		PR79B	3	
AC4	PR65A	3		PR79A	3	
AE7	PR64D	3		PR78D	3	
AD7	PR64C	3		PR78C	3	
AD5	PR64B	3		PR78B	3	
AC5	PR64A	3		PR78A	3	
AD6	PR63D	3		PR77D	3	
AC6	PR63C	3		PR77C	3	
AB1	PR63B	3		PR77B	3	
AA1	PR63A	3		PR77A	3	
AD9	PR61D	3		PR75D	3	
AC9	PR61C	3		PR75C	3	
AB2	PR61B	3		PR75B	3	
AA2	PR61A	3		PR75A	3	
AD14	PR60D	3		PR74D	3	
AC14	PR60C	3		PR74C	3	
AB5	PR60B	3		PR74B	3	
AA5	PR60A	3		PR74A	3	
AD10	PR59D	3		PR73D	3	
AC10	PR59C	3		PR73C	3	
Y1	PR59B	3		PR73B	3	
W1	PR59A	3		PR73A	3	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB25	VCC	-		VCC	-	
AB26	VCC	-		VCC	-	
AC16	VCC	-		VCC	-	
AC18	VCC	-		VCC	-	
AC20	VCC	-		VCC	-	
AC23	VCC	-		VCC	-	
AC25	VCC	-		VCC	-	
AC27	VCC	-		VCC	-	
AD17	VCC	-		VCC	-	
AD19	VCC	-		VCC	-	
AD21	VCC	-		VCC	-	
AD22	VCC	-		VCC	-	
AD24	VCC	-		VCC	-	
AD26	VCC	-		VCC	-	
AE16	VCC	-		VCC	-	
AE18	VCC	-		VCC	-	
AE20	VCC	-		VCC	-	
AE21	VCC	-		VCC	-	
AE22	VCC	-		VCC	-	
AE23	VCC	-		VCC	-	
AE25	VCC	-		VCC	-	
AE27	VCC	-		VCC	-	
AF17	VCC	-		VCC	-	
AF19	VCC	-		VCC	-	
AF21	VCC	-		VCC	-	
AF22	VCC	-		VCC	-	
AF24	VCC	-		VCC	-	
AF26	VCC	-		VCC	-	
AG18	VCC	-		VCC	-	
AG20	VCC	-		VCC	-	
AG23	VCC	-		VCC	-	
AG25	VCC	-		VCC	-	
T18	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
T23	VCC	-		VCC	-	
T25	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
U22	VCC	-		VCC	-	
U24	VCC	-		VCC	-	
U26	VCC	-		VCC	-	
V16	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1,2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH22	VTT_5	5		VTT_5	5	
AJ22	VTT_5	5		VTT_5	5	
AJ23	VTT_5	5		VTT_5	5	
AJ24	VTT_5	5		VTT_5	5	
AJ25	VTT_5	5		VTT_5	5	
AB28	VTT_6	6		VTT_6	6	
AB29	VTT_6	6		VTT_6	6	
AE29	VTT_6	6		VTT_6	6	
AJ30	VTT_6	6		VTT_6	6	
AA28	VTT_7	7		VTT_7	7	
AA29	VTT_7	7		VTT_7	7	
R31	VTT_7	7		VTT_7	7	
V29	VTT_7	7		VTT_7	7	
Y24	GND	-		GND	-	
Y26	GND	-		GND	-	
Y8	GND	-		GND	-	
Y35	GND	-		GND	-	
AA16	VCC12	-		VCC12	-	
AA27	VCC12	-		VCC12	-	
AB16	VCC12	-		VCC12	-	
AB27	VCC12	-		VCC12	-	
AF16	VCC12	-		VCC12	-	
AF27	VCC12	-		VCC12	-	
AG17	VCC12	-		VCC12	-	
AG21	VCC12	-		VCC12	-	
G33	NC	-		NC	-	
G10	NC	-		NC	-	
M15	NC	-		NC	-	
L15	NC	-		NC	-	
K16	NC	-		NC	-	
J16	NC	-		NC	-	
M18	NC	-		NC	-	
L18	NC	-		NC	-	
M25	NC	-		NC	-	
L25	NC	-		NC	-	
J27	NC	-		NC	-	
K27	NC	-		NC	-	
L28	NC	-		NC	-	
M28	NC	-		NC	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M80 and LatticeSC/M115 in a 1704-pin package supports a 32-bit MPI interface.

Industrial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA115E-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	115.2
LFSC3GA115E-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSC3GA115E-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	115.2
LFSC3GA115E-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSC3GA115E-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152I ¹	-6	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FC1152I ¹	-5	Ceramic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FF1152I	-6	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-5FF1152I	-5	Organic fcBGA	1152	IND	115.2
LFSCM3GA115EP1-6FC1704I ¹	-6	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FC1704I ¹	-5	Ceramic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-6FF1704I	-6	Organic fcBGA	1704	IND	115.2
LFSCM3GA115EP1-5FF1704I	-5	Organic fcBGA	1704	IND	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).